Attorney Docket No.: 018865-004210US

I hereby certify that this is being deposited with the United States Postal Service "Express Mail Post Office to Address" service under 37 CFR 1.10 on the date indicated above and is addressed to:

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Joshi et al.

Application No.: Unassigned

Filed: Herewith

For: FLIP CHIP IN LEADED MOLDED PACKAGE AND METHOD OF

MANUFACTURE THEREOF

Examiner:

Luan Thai

Technology Center/Art Unit: 2812

PRELIMINARY AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Prior to examination of the above-referenced application, please enter the

following amendments and remarks:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Amendments to the Drawings begin on page 3 of this paper and include an attached replacement sheet.

Remarks/Arguments begin on page 6 of this paper.